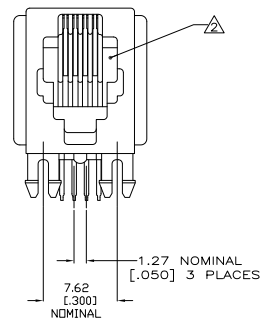
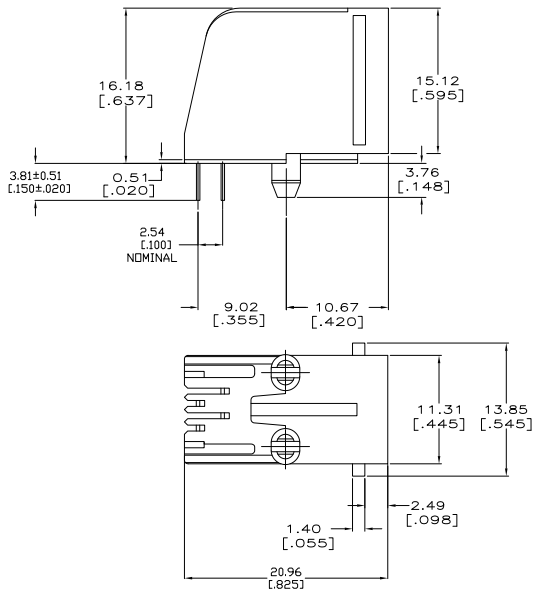
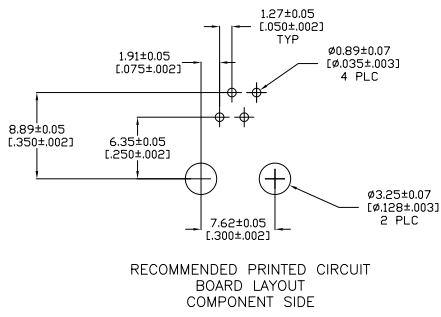
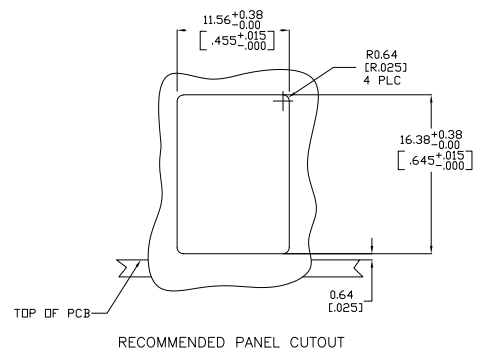


THIS DRAWING IS UNPUBLISHED
 ALL RIGHTS RESERVED

REV	DATE	DESCRIPTION	BY	CHK
AA	00			
D1		REVISED PER EDD-11-005033	23MAR11	RK HMR



- MATERIAL:
 HOUSING - POLYESTER, UL-94-V0, COLOR; BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH (SEE TABLE) MIN HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81 PE 76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 0.15µm[.000006] GOLD PLATED PARTS DO NOT MEET THE MINIMUM GOLD THICKNESS REQUIREMENT OF FCC SPECIFICATION, PART 68. PARTS HAVE NOT BEEN TESTED TO THE DURABILITY REQUIREMENTS OF TE CONNECTIVITY PRODUCT SPEC 108-1163.



0.15µm[.000006]	2-5520249-2
1.27µm[.000050]	5520249-2
GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		TE CONNECTIVITY	
UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	TE CONNECTIVITY	TE Connectivity
DIMENSIONS (mm INCHES)	FINISHES	108-1163	PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, SIDE ENTRY, 4 POSITION, FLANGELESS, WITH PANEL STOPS
PLATE	PLATE	114-2048	REWORKED TO
SEE NOTE 1	SEE NOTE 1	A1 00779	5520249
		CUSTOMER DRAWING	REV: 5.1 SHEET 1 OF 1